



Ultra-low Power Bluetooth Audio Platform

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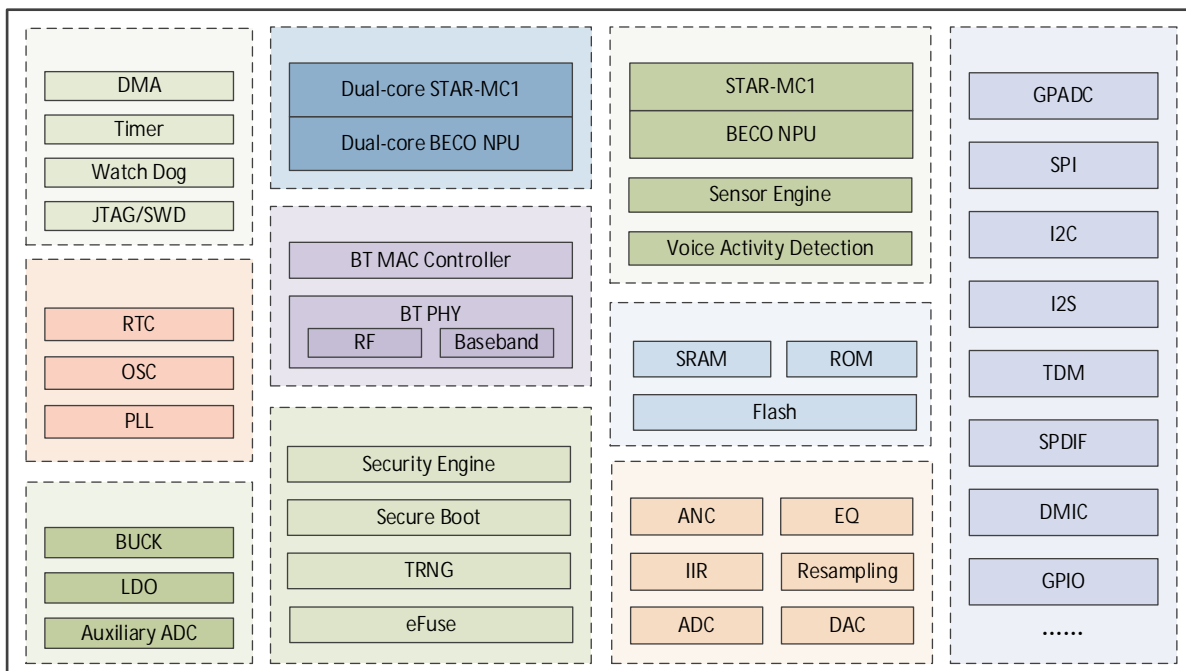
For product inquiries and more information, please visit www.bestechnic.com.

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The BES2700H is an ultra-low power Bluetooth audio SoC. The platform incorporates a high performance CPU subsystem comprising a dual-core STAR-MC1 processor with a dual-core BECO NPU, a BES proprietary coprocessor for advance signal processing and NN workloads, and a sensor hub subsystem comprising a STAR-MC1 processor with a BECO NPU, RAM/ROM, serial flash for software features and product customization, as well as a variety of interfaces.

The platform integrates a dual-mode Bluetooth 5.4 subsystem for both Bluetooth classic and LE audio, and an audio codec subsystem supporting voice activity detection. The highly integrated design minimizes external components, reduces BOM costs and offers a cost-effective Bluetooth audio solution.



- Smart headphones/headsets with adaptive ANC
- Bluetooth speakers with LE audio
- Other portable audio devices

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|------------------------|--|
| CPU Subsystem | Dual-core STAR-MC1 |
| Sensor Hub Subsystem | STAR-MC1 |
| | Sensor engine |
| Memory and Storage | Shared 2.2 MB SRAM |
| | Flash in package |
| | boot ROM |
| Bluetooth Subsystem | Dual-mode BT 5.4 with LE audio |
| Audio & Voice Features | 2x DACs |
| | 5x ADCs |
| Peripheral Interfaces | GPADC/eMMC/SPI/I2C/UART/I2S/TDM/SPDIF/DMIC/PWM/GPIO..... |
| Package | 219-pin BGA |

* The content in the table is subject to change without notice.